



Thermal Innovations for a Cool World

T W E N T Y - E I G H T H A N N U A L  
 Semiconductor Thermal Measurement, Modeling and Management Symposium  
 DoubleTree Hotel, San Jose, CA, USA  
 March 18-22, 2012

## CALL FOR PAPERS

SEMI-THERM is a premier international forum on the thermal management of semiconductors in electronics. The symposium fosters the exchange of knowledge between thermal engineers, professionals and leading experts from industry as well as the exchange of information on the latest academic and industrial advances in electronics thermal management.

In its 28<sup>th</sup> year, SEMI-THERM will include Invited Speakers, Technical Sessions, Short Courses and an Evening Tutorial as well as vendor exhibits and dedicated vendor sessions for the latest in commercial offerings. SEMI-THERM actively solicits student papers and awards travel stipends and reduced conference fees. Those papers deemed to be among the best in the conference will be invited to be published in *IEEE Transactions on Components and Packaging Technologies*.

### Subjects of Particular Interest

SEMI-THERM is soliciting papers on current thermal management technologies and practical application issues, modeling and measurement of electronic components and systems including but not limited to, the following areas:

Industries/Application Environments	Electronic Cooling	Fundamental Science
<b>T1: Alternative and Renewable Energy</b> Solar, Wind, Nuclear, Electric and Hybrid vehicles <b>T2: LED Lighting</b> <b>T3: Data Center</b> Metrics, Best Practices, Efficient Layout, Industry Trends <b>T4: IT Equipment</b> Network Equipment, Servers, Storage Devices, PCs, Laptops <b>T5: Portable and Consumer Electronics</b> Cell Phones, PDAs, Game Consoles, Tablet <b>T6: Power Electronics</b> Discrete Board Components, VRMs, Power Supplies, IGBTs <b>T7: Harsh Environments</b> Military, Aerospace, Industrial, Automotive <b>T8: Medical and Biomedical</b>	<b>T9: Packaging</b> Components- Die and Package, Boards, and Systems <b>T10: Thermal Packaging Materials</b> TIMs, Heat Spreaders, Laminates, Nanomaterials, Composites <b>T11: Analysis and Modeling</b> CFD, FEA, Engineering Calculations, Novel Approaches <b>T12: Experimental Work</b> Air and Liquid Cooling Systems, Component Level Characterizations, DOE, Error Analysis <b>T13: Thermal Design Process</b> Thermal aware design <b>T14: Multidisciplinary Thermal Management</b> Design Trade-offs for Acoustics, Cost, Reliability	<b>T15: Heat Transfer Fundamentals</b> Conduction, Convection, Radiation <b>T16: Air Cooling</b> <b>T17: Liquid Cooling</b> Single Phase, Two Phase, Multi-phase, Vapor Compression/ Refrigeration <b>T18: Thermal Components</b> Heat Sinks, Peltier and Thermal Electric Devices, Air Movers- Fans, Blowers, Solid State <b>T19: Thermal Measurement Techniques and Technology</b>

Selection of papers for presentation is solely based on an **extended** abstract. The abstract should provide a complete summary of the proposed paper comprising work or results not previously presented or published. Submitted abstracts should be between 2 and 5 pages of single spaced text giving the key results, findings and conclusions, supported by additional pages of figures, tables and references as appropriate. **Abstracts must demonstrate that the proposed papers are appropriate for SEMI-THERM and of high technical quality.** Abstracts must be submitted electronically in RTF, DOC or PDF formats via the SEMI-THERM web site.

The intent of technical papers is to communicate timely and relevant technical information to a technical audience. The paper should present an unbiased description of a certain method or product that discusses both pros and cons. Both subtle and blatant advertisement of any products or services is in direct conflict with the spirit of the Symposium. Examples of the former include repeated references to products or trade names and excessive use of corporate logos and trademarks in graphic illustrations. Photographs of commercial equipment are not permitted unless they add educational value. The SEMI-THERM Program Committee desires that all authors and presenters understand unambiguously that commercialism is inappropriate and will not be tolerated; authors are asked to abide by these constraints when preparing their abstracts, papers, and presentations.

### Deadlines

Abstract Deadline	Abstract Acceptance Notification	Photo-ready Full Manuscript Due
September 12, 2011 Extended to September 26, 2011	October 31, 2011	January 2, 2012

For further information please contact the Program Chair via email:

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Visit the SEMI-THERM web site at: <http://www.semi-therm.org>